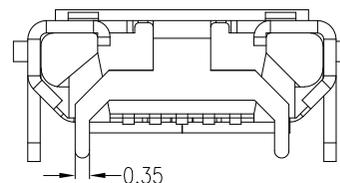
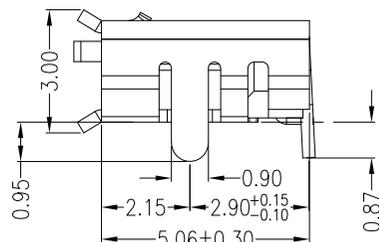
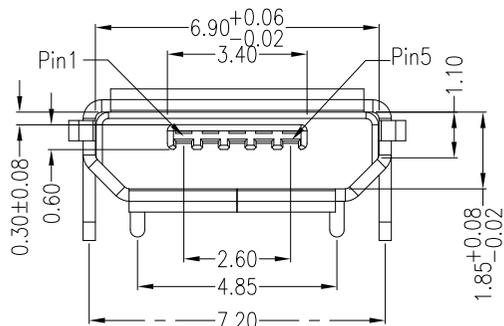
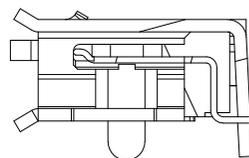
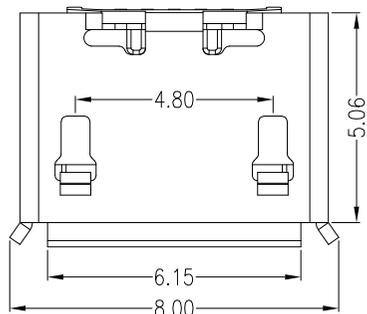


# GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2022/03/30	Ken Lin



Note:

1.Material:

- 1.1 Housing: High temperature thermoplastic with g.f,UL94v-0,LCP,BLACK
- 1.2 Contact: copper alloy,t=0.20mm
- 1.3 Shell: SUS,t=0.25mm
- contact: 3u" Gold Plated on contact Area , 50u"Min.nickel underplating over all.
- Shell:30u"MIN.Nickel Underplating Over All.

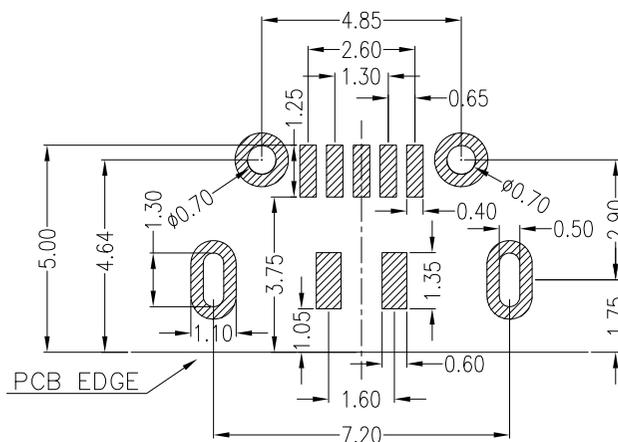
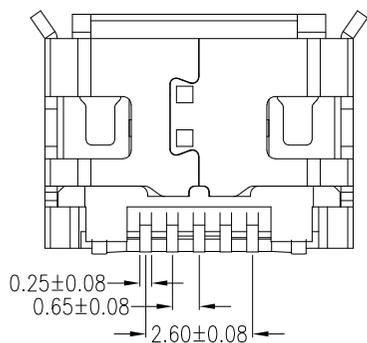
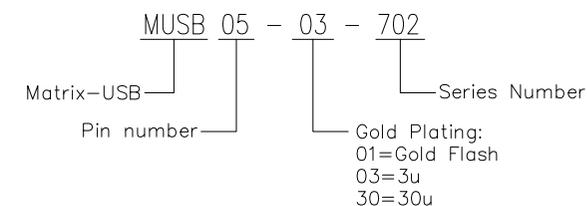
2.Specification:

- 2.1 Current rating:1,5PIN 1.8A Max/2,3,4PIN 1A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 30 mΩ Max.
- 2.4 Insulation resistance: 100 MΩ Min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf Min.
- 2.7 Temperature range: -40°C~105°C

3.MECHANICAL SPECIFICATION:

- MATING FORCE:35N MAX
- UNMATING FORCE:8N MIN
- DURABILITY:3000 CYCLES

MATRIX PART NO:



PCB 图仅做参考  
(TOP VIEW)



Matrix Electronics Co.,Ltd

<b>TOLERANCE:</b> X:X ±0.38 X:XX ±0.25 X:XXX ±0.10 ANGLE: ±3°	DESIGN BY :	DATE :	PART NAME:	
	Ken Lin	2022/03/30	Micro USB 5F B TYPE牛角插板7.2	
UNIT: mm [inch] SCALE:1:1 SIZE:A4	CHECKED BY:	DATE :	PART NO.	MUSB05-03-702
	Vicky Hsieh	2022/03/30		
APPROVED BY1: Richard Hsieh APPROVED BY2: Richard Hsieh	DATE :	MOLD NO.	NA	
	2022/03/30			
		DATE :	DRAW NO.	
		2022/03/30	SHEET NO.	1 OF 1